Appl. No. : **10/752,666**
Filed : **January 8, 2004**

AMENDMENTS TO THE CLAIMS

Please amend Claims 1-11 as follows:

1. (Currently Amended) A method for making an optical interference type display panel, the method comprising the steps of:

providing a substrate (10);

sequentially forming a plurality of first conductive optical film stacks (20), a supporting layer (11), a spacing layer (12) and a plurality of second conductive optical film stacks (13) on the substrate (10); and

forming a plurality of connecting pads (201)(202) near edges of the substrate (10), wherein the plurality of connecting pads (201)(202) ~~is made of~~ comprises a transparent conductive layer (21) of the first conductive optical film stack (20).

2. (Currently Amended) The method as claimed in claim 1, the method further comprising the steps of:

forming ~~the~~ [a] plurality of separated first conductive optical film stacks (20) on the substrate (10);

defining patterns of connecting pads, wherein portions of these separated first conductive optical film stacks (20) are further patterned to form the plurality of connecting pads (201)(202);

forming the supporting layer (11) on the substrate (10), wherein the supporting layer (11) is formed between two separated first conductive optical film stacks (20);

forming the spacing layer (12), wherein the spacing layer (12) is formed above each separated first conductive optical film stack (20) and is further flattened;

forming the plurality of second conductive optical film stacks (13), wherein these second conductive optical film stacks (13) are coated on the spacing layer (12) and the supporting layer (11), and the second conductive optical film stacks (13) are electrically connected to at least a portion of the plurality of the connecting pads (202); and

removing the spacing layer (12), wherein once the spacing layer (12) has been removed from the substrate (10), a gap is defined between the first and the second conductive optical film stacks (20)(13).

3. (Currently Amended) The method as claimed in claim 1, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a transparent conductive layer (21a), an absorption layer (22a) and a dielectric layer (24a) on the substrate (10).

4. (Currently Amended) The method as claimed in claim 2, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a transparent conductive layer (21a), an absorption layer (22a) and a dielectric layer (24a) on the substrate (10).

5. (Currently Amended) The method as claimed in claim 1, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a first dielectric layer (23b), a transparent conductive layer (21b), an absorption layer (22b) and a second dielectric layer (24b) on the substrate (10).

6. (Currently Amended) The method as claimed in claim 2, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a first dielectric layer (23b), a transparent conductive layer (21b), an absorption layer (22b) and a second dielectric layer (24b) on the substrate (10).

7. (Currently Amended) The method as claimed in claim 1, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a transparent conductive layer (21c), a first dielectric layer (23c), an absorption layer (22c) and a second dielectric layer (24c) on the substrate (10).

8. (Currently Amended) The method as claimed in claim 2, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a transparent conductive layer (21c), a first dielectric layer (23c), an absorption layer (22c) and a second dielectric layer (24c) on the substrate (10).

9. (Currently Amended) The method as claimed in claim 1, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a first dielectric layer (23d), an absorption layer (22d) a transparent conductive layer (21d) and a second dielectric layer (24d) on the substrate (10).

10. (Currently Amended) The method as claimed in claim 2, wherein forming the first conductive optical film stack (20) ~~is formed by~~ comprises the step of:

sequentially forming a first dielectric layer (23d), an absorption layer (22d) a transparent conductive layer (21d) and a second dielectric layer (24d) on the substrate (10).

11. (Currently Amended) An optical interference display panel comprising:

a substrate on which a plurality of first conductive optical film stacks (20), a supporting layer (11) and a plurality of second conductive optical film stacks (13) are formed; and

a plurality of connecting pads (201)(202) formed near edges of the substrate (10), wherein the plurality of connecting pads (201)(202) ~~are made of~~ comprises a transparent conductive layer (21) of the first conductive optical film stack (20).

12. (Original) The display panel as claimed in claim 11, the first conductive optical film stack (20) comprising a transparent conductive layer (21a), an absorption layer (22a) and a dielectric layer (24a) on the substrate (10), which are sequentially formed on the substrate (10).

13. (Original) The display panel as claimed in claim 11, the first conductive optical film stack (20) comprising a first dielectric layer (23b), a transparent conductive layer (21b), an absorption layer (22b) and a second dielectric layer (24b), which are sequentially formed on the substrate (10).

14. (Original) The display panel as claimed in claim 11, the first conductive optical film stack (20) comprising a transparent conductive layer (21c), a first dielectric layer (23c), an absorption layer (22c) and a second dielectric layer (24c), which are sequentially formed on the substrate (10).

15. (Original) The display panel as claimed in claim 11, the first conductive optical film stack (20) comprising a first dielectric layer (23d), an absorption layer (22d) a transparent conductive layer (21d) and a second dielectric layer (24d), which are sequentially formed on the substrate (10).